

Service : Final Test

Note: find description of test equipment at end of this file

Purpose

Electrical test of packaged parts
Test data recording
Separation of failing devices

Benefits

Delivery of untested parts is no option as there is always a percentage of defects. Even parts that have passed a test on wafer level before bear the risk of defects induced by the packaging process.

Bluetest Expertise

Electrical test of semiconductor devices on wafer and packaged level is core competence of Bluetest, based on experience from 30 years in test. Our infrastructure and equipment (lab, handling systems, wafer prober, test system) and also our organisation are focussed on high quality and high throughput at small test time.

Activities

Participants

Test, Operator

Requirements, Input

Devices
Test program, test hardware, test instructions

Performance

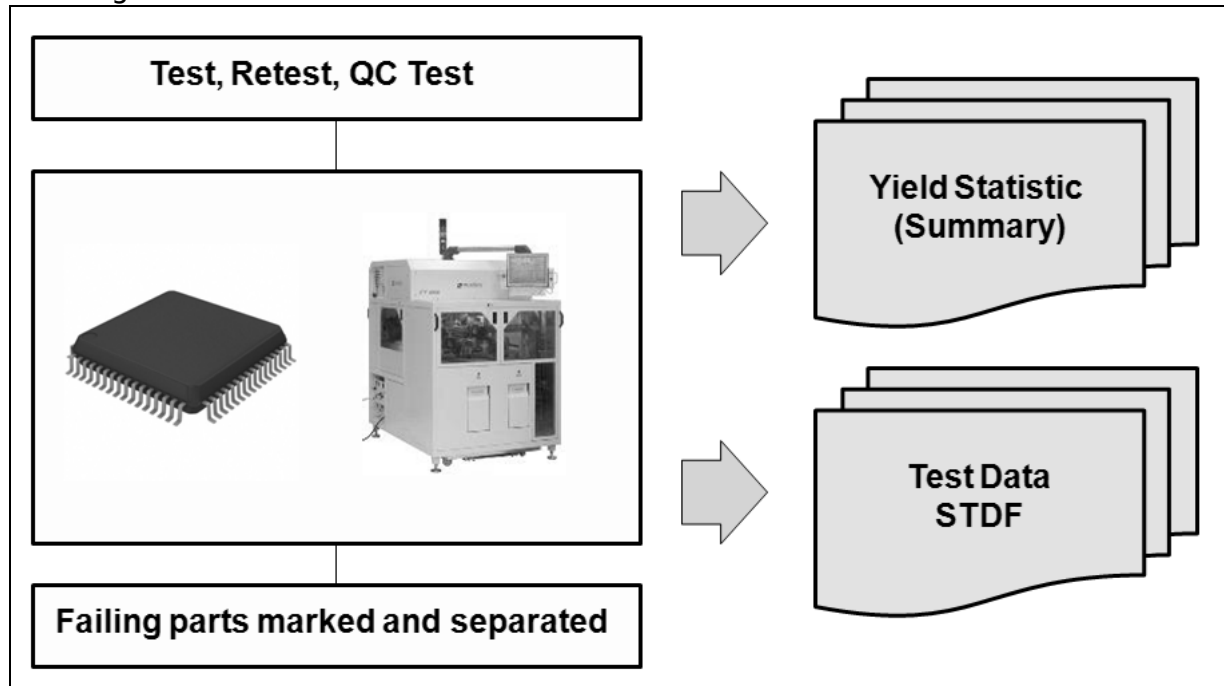
Correct setup of equipment and identification of the right test program are specified in test instructions which are part of our intranet based QM-Documentation. They contain also stop and alarm limits for test yield and reaction plans in case of troubles.

Testing is performed using automatic handling systems or in manual mode if no handling system is available for a package type.

The long test time has to be balanced against the NRE of a handling system and kit.

Result, Output

Drawing: results from final test



Comments:

Retest = repeated test of devices that failed first test

QC- Test = sample test (AQL) as quality gate

Final test equipment:

Mixed Signal Test system - LTX-Credence D10

- * 192 digital channels
- * 16MB Vector memory
- * APG, SCAN
- * 16 4-Quadrant VI sources
- * Multiwave with 4 arbitrary waveform generators and 4 digitizer
- * Easy integration of external measurement equipment

Multitest 9510 3-Temperature Pick&Place Handling System

Multitest 8704 IHF ambient and hot Handling System

Microtec MH240 ambient Handling System